

# LNJ253W82RA

## Hight Bright Surface Mounting Chip LED

SV (Side View) -0.5 Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	55	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Lighting Color

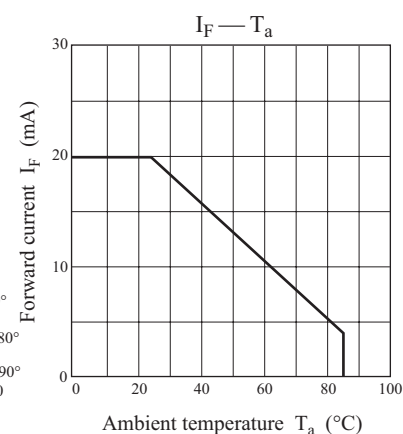
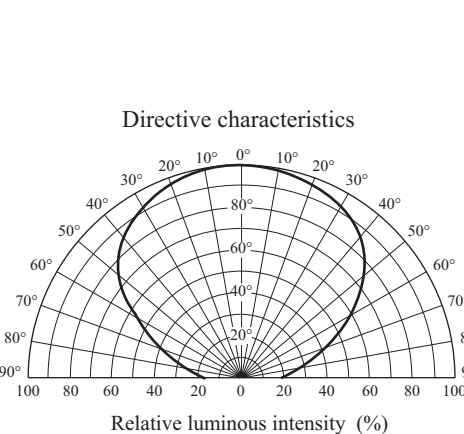
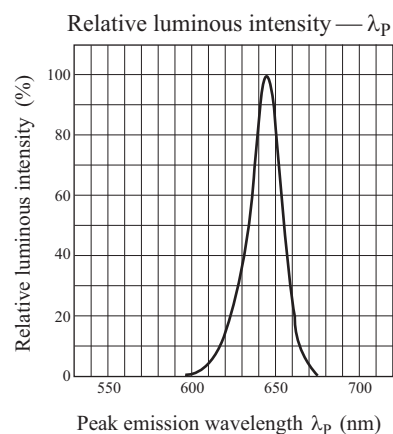
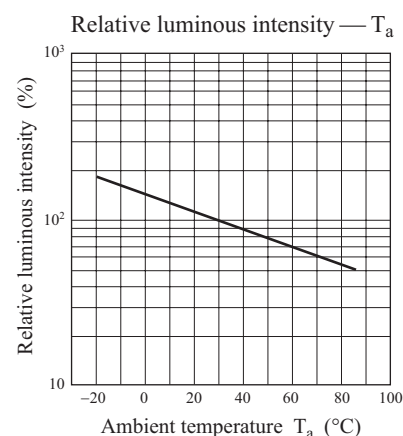
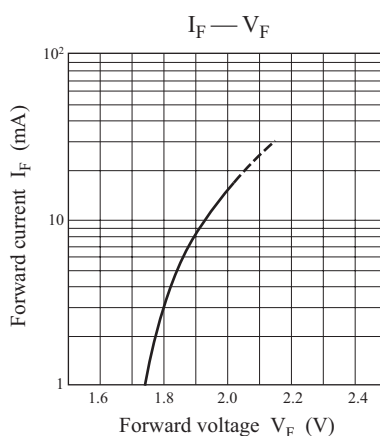
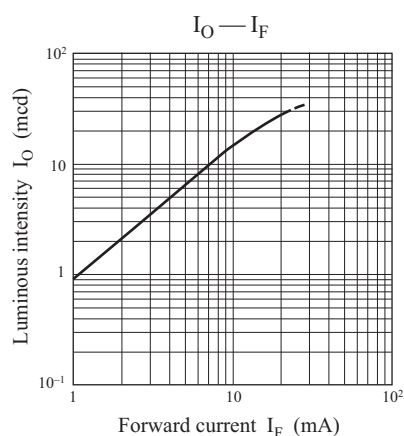
- Red

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

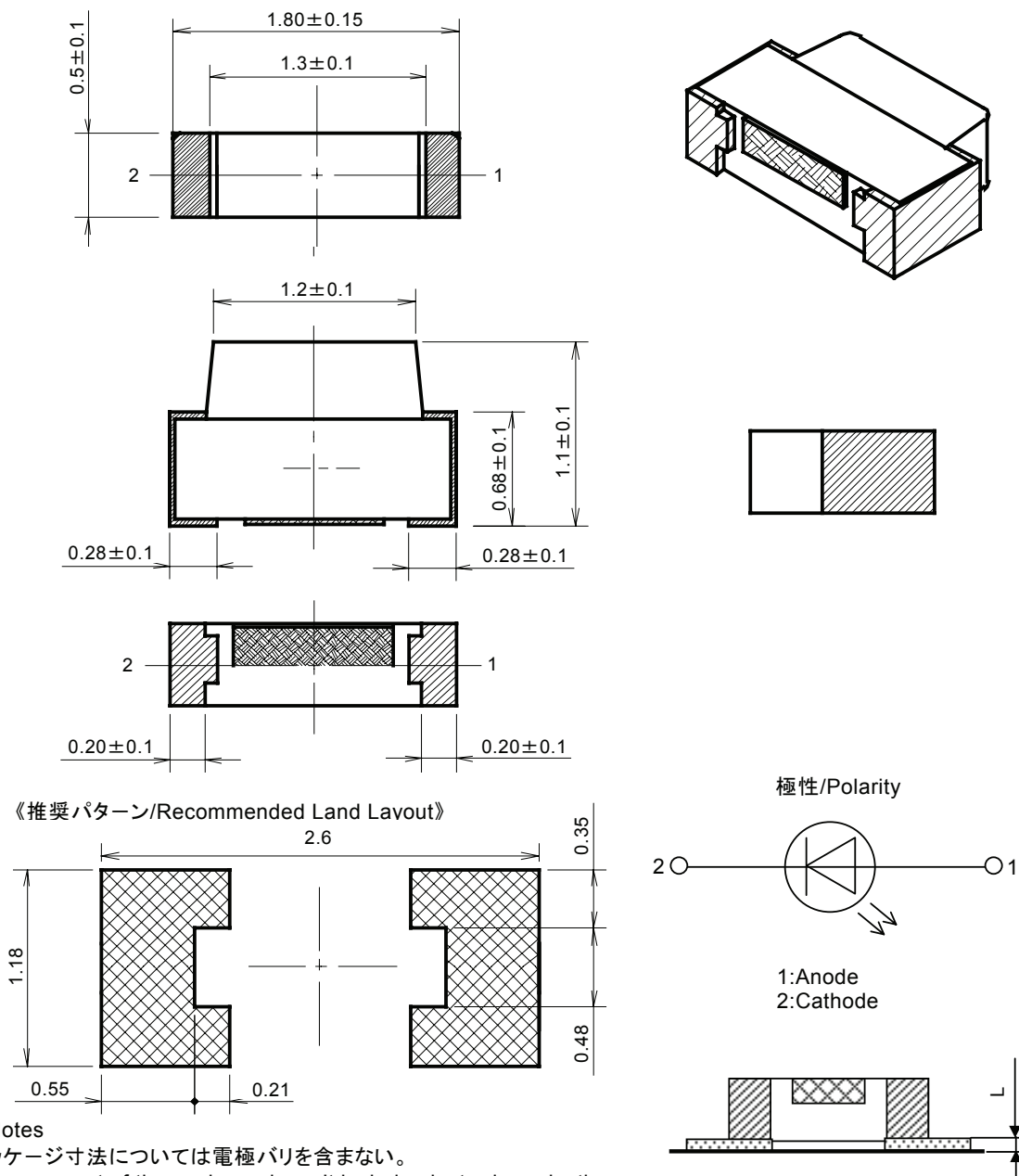
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	$I_O$	$I_F = 10\text{ mA}$	8.0	15.0	60.8	mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		1.92	2.5	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		645		nm
Dominant emission wavelength *2	$\lambda_d$	$I_F = 10\text{ mA}$	620	630	640	nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		22		nm

Note) \*1: Measurement tolerance:  $\pm 20\%$

\*2: Measurement tolerance:  $\pm 3\text{ nm}$



■ Package (Unit: mm)



注記/Notes

1. パッケージ寸法については電極バリを含まない。  
Measurement of the package doesn't include electrode projection.
2. 当製品は工法上、はんだ付け面端子端部にメッキバリカエリが発生することや、製品背面部に端子を有する縦型面実装タイプである為、リフローはんだ付けの際に不濡れ等が懸念されます。従いまして、はんだの種類の検討ならびに各パットに対し、適正なはんだ量を考慮してください。  
Precaution to soldering  
Assembly conditions such like mechanical lode in placing LED and also suitable volume and type of solder paste has to be fully investigated.  
Insufficient soldering may occur because of the condition of solder terminal surface which is caused is caused by its unique production process.
3. 基本的に LED 直下範囲には固着フットパターン厚み(L)以上のシルク印刷をしないでください。  
Please do not print silk more than fixture foot pattern thickness (L) basically within the range right under the LED.

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